

# METHOD FOR JOINING LARGE SUBSTRATES

## Abstract of the Disclosure

A method for joining large area semiconductor substrates, a liquid thermoset polymer. Two large area substrates, such as wafers or circuit boards (e.g., rigid or flexible), can be joined together by dispensing a liquid polymer inwardly from the edges of the semiconductor substrates. The substrates can then be pressed together so that the liquid thermoset flows in an outwardly direction ward the edges of the semiconductor substrates. Conducting surfaces on the first and second substrates may contact each other after pressing the liquid thermoset polymer. The liquid thermoset polymer in the formed structure may then be cured to a hardened state. The liquid thermoset polymer preferably has a low viscosity, low levels of ionic contaminants, good adhesion to the substrates, low moisture absorbing properties and favorable thermal expansion properties.

Patent Office